

AMENDMENTS

In The Claims

Please amend the claims as follows.

1. (Twice amended) A substrate structure of Flip Chip package comprising:

a plurality of patterned circuit layers;

at least an insulative layer stacked between the patterned circuit layers for isolating the patterned circuit layers, and the patterned circuit layers are electrically connected one another, and one of the patterned circuit layer is positioned on the surface of the substrate of the flip chip package as a top patterned circuit layer, and the top patterned circuit layer comprises at least a plurality of first mounting pads and a plurality of second mounting pads; and

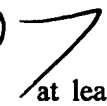
a solder mask layer covering the patterned circuit layer on the surface of the substrate of the flip chip package, the solder mask layer partially covering a first top surface of the first mounting pads while entirely exposing a second top surface and sidewalls of the second mounting pads, wherein the first mounting pads are disposed at a peripheral region of the substrate and the second mounting pads are disposed at a central region of the substrate.

2. (Once amended) The substrate structure of Flip Chip package of claim 1 wherein the

material for the insulative layer is selected from the group consisting of flame-retardant epoxy-glass fabric composite resin, Bismaleimide-Triazine (BT), and epoxy.

7. (Twice amended) A substrate structure of Flip Chip package comprising:

a plurality of patterned circuit layer;

could be 

at least an insulative layer stacked between the patterned circuit layers for isolating the patterned circuit layers, and the patterned circuit layers are electrically connected one another, and one of the patterned circuit layer is positioned on the surface of the substrate of the flip chip package as a top patterned circuit layer, and the top patterned circuit layer comprises at least a plurality of first mounting pads and a plurality of second mounting pads;

*3
B
cont*

a solder mask layer covering the top patterned circuit layer on the surface of the substrate of the flip chip package, the solder mask layer partially covering a first top surface of the first mounting pads while entirely exposing a second top surface and sidewalls of the second mounting pads, wherein the first mounting pads are formed at a peripheral region of the substrate;

a chip having an active surface with a plurality of bumps disposed thereon wherein the chip has its active surface face to the surface of the substrate of the flip chip package, and the bumps are electrically connected to their corresponding first bonding pads and second bonding pads respectively; and

an underfill material filling between the active surface of the chip and the top surface of the substrate of the flip chip package.

B7-D1

8. (Once amended) The substrate structure of Flip Chip package of claim 7 wherein the material for the insulative layer is selected from the group consisting of flame-retardant epoxy-glass fabric composite resin, Bismaleimide-Triazine (BT), and epoxy.